Patent Details

Title of the Patent	**:**	Mouldable Polymer Composites with Thermal Conductivity and EMI Shielding
Patentee	**:**	Central Institute of Petrochemicals Engineering & Technology (CIPET)
Name of the Inventors	**:**	1. Prof. (Dr.) Sanjay K. Nayak 2. Dr. Smita Mohanty 3. Dr. Lakshmi Unnikrishnan 4. Mr. Subhransu S. Pradhan
Application Number	**:**	201931010082
Filing Date	**:**	15.03.2019
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Summary of the Innovation/ Patent/ Technology	**:**	**Invention details:** A mouldable polymer composition with effective thermal dissipation and a polymer composition with carbon based conductive fillers that offer better electromagnetic interference shielding.
		Importance of technology Faster transfer of thermal energy in the high strength polymer composition bestowed with desired functional performance and EMI
		Viability of commercialization: The composite material can suitably substitute the Aluminum based mouldings with ease of processibility and EMI
		Benefit to society: Light weight mouldings and better performance
Graphical Abstract/ Image of the Product	**:**	